

# DATA SHEET

## ANTI-SULFURATED CHIP RESISTORS

AF series

5%, 1%

sizes 0402/0603/0805/1206

RoHS compliant & Halogen free





**MARKING**

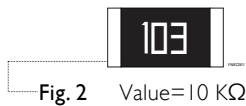
**AF0402**



No marking

Fig. 1

**AF0603 / AF0805 / AF1206**



E-24 series: 3 digits,  $\pm 5\%$ ,  $\geq 10 \Omega$   
 First two digits for significant figure and 3rd digit for number of zeros

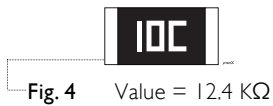
Fig. 2 Value = 10 K $\Omega$

**AF0603**



E-24 series: 3 digits,  $\pm 1\%$   
 One short bar under marking letter

Fig. 3 Value = 24  $\Omega$



E-96 series: 3 digits,  $\pm 1\%$   
 First two digits for E-96 marking rule and 3rd letter for number of zeros

Fig. 4 Value = 12.4 K $\Omega$

**AF0805 / AF1206**



Both E-24 and E-96 series: 4 digits,  $\pm 1\%$   
 First three digits for significant figure and 4th digit for number of zeros

Fig. 5 Value = 10 K $\Omega$

**NOTE**

For further marking information, please see special data sheet "Chip resistors marking". Marking of AF series is the same as RC series

**CONSTRUCTION**

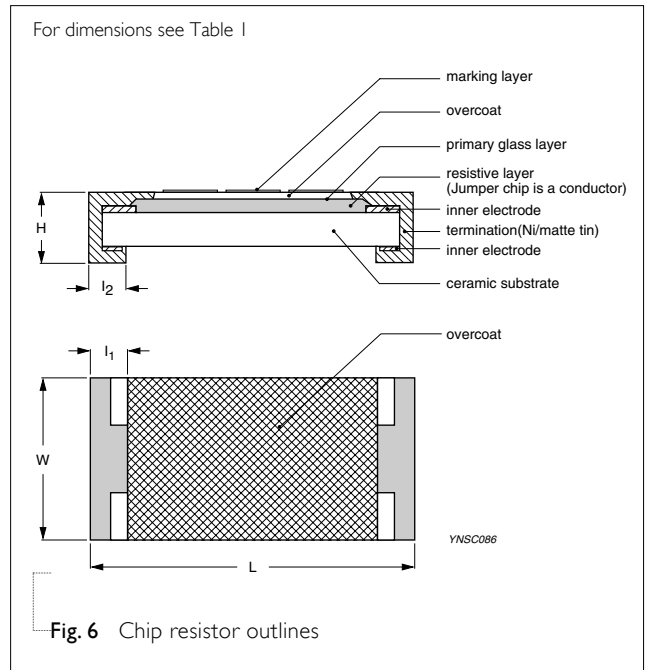
The resistors are constructed on top of a high grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive glaze. The resistive glaze is covered by a lead-free glass. The composition of the glaze is adjusted to give the approximate required resistance value and laser trimming of this resistive glaze achieves the value within tolerance. The whole element is covered by a protective overcoat. Size 0603 and bigger is marked with the resistance value on top. Finally, the two external terminations (Ni / matte tin) are added. See fig.6

**DIMENSIONS**

Table I For outlines see fig. 6

TYPE	L (mm)	W (mm)	H (mm)	I <sub>1</sub> (mm)	I <sub>2</sub> (mm)
AF0402	1.00 ±0.05	0.50 ±0.05	0.32 ±0.05	0.20 ±0.10	0.25 ±0.10
AF0603	1.60 ±0.10	0.80 ±0.10	0.45 ±0.10	0.25 ±0.15	0.25 ±0.15
AF0805	2.00 ±0.10	1.25 ±0.10	0.50 ±0.10	0.35 ±0.20	0.35 ±0.20
AF1206	3.10 ±0.10	1.60 ±0.10	0.55 ±0.10	0.45 ±0.20	0.40 ±0.20

**OUTLINES**



**ELECTRICAL CHARACTERISTICS**

Table 2

TYPE	RESISTANCE RANGE	CHARACTERISTICS				Temperature Coefficient of Resistance
		Operating Temperature Range	Max. Working Voltage	Max. Overload Voltage	Dielectric Withstanding Voltage	
AF0402			50 V	100 V	100 V	
AF0603	±5% (E24), 1 Ω to 22 MΩ		50 V	100 V	100 V	1 Ω ≤ R ≤ 10 Ω, ±200 ppm/°C
AF0805	±1% (E24/E96), 1 Ω to 10 MΩ Zero Ohm Jumper < 0.05 Ω	-55 °C to +155 °C	150 V	300 V	300 V	10 Ω < R ≤ 10 MΩ, ±100 ppm/°C
AF1206			200 V	400 V	500 V	10 MΩ < R ≤ 22 MΩ, ±200 ppm/°C

**FOOTPRINT AND SOLDERING PROFILES**

For recommended footprint and soldering profiles of AF-series is the same as RC-series. Please see the special data sheet “Chip resistors mounting”.

**PACKING STYLE AND PACKAGING QUANTITY**

Table 3 Packing style and packaging quantity

PACKING STYLE	REEL DIMENSION	AF0402	AF0603	AF0805	AF1206
Paper taping reel (R)	7" (178 mm)	10,000/20,000	5,000	5,000	5,000
	10" (254 mm)	20,000	10,000	10,000	10,000
	13" (330 mm)	50,000	20,000	20,000	20,000

**NOTE**

I. For paper/embossed tape and reel specification/dimensions, please see the special data sheet “Chip resistors packing”.

**FUNCTIONAL DESCRIPTION**

**OPERATING TEMPERATURE RANGE**

Range: -55 °C to +155 °C

**POWER RATING**

Each type rated power at 70 °C:

AF0402=1/16 W (0.0625W)

AF0603=1/10 W (0.1W)

AF0805=1/8 W (0.125W)

AF1206=1/4 W (0.25W)

**RATED VOLTAGE**

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

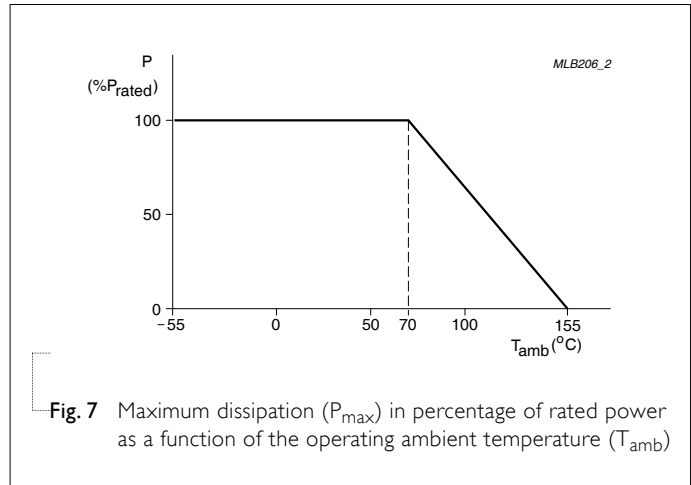
$$V = \sqrt{P \times R}$$

Where

V = Continuous rated DC or AC (rms) working voltage (V)

P = Rated power (W)

R = Resistance value ( $\Omega$ )



**TESTS AND REQUIREMENTS**
**Table 4** Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature Coefficient of Resistance (T.C.R.)	IEC 60115-1 4.8	At +25/-55 °C and +25/+125 °C  <b>Formula:</b> $T.C.R = \frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$  Where t <sub>1</sub> =+25 °C or specified room temperature t <sub>2</sub> =-55 °C or +125 °C test temperature R <sub>1</sub> =resistance at reference temperature in ohms R <sub>2</sub> =resistance at test temperature in ohms	Refer to table 2
Life/Endurance	IEC 60115-1 4.25 MIL-STD-202 Method 108	At 70±2 °C for 1,000 hours, RCWV applied for 1.5 hours on, 0.5 hour off, still air required	±(1.0%+0.05 Ω) <100 mΩ for Jumper
High Temperature Exposure/Endurance at Upper Category Temperature	MIL-STD-202 Method 108	1,000 hours at 155±5 °C, unpowered	±(1.0%+0.05 Ω) for 1% tol. ±(1.0%+0.05 Ω) for 5% tol. <100 mΩ for Jumper
Moisture Resistance	MIL-STD-202 Method 106	Each temperature / humidity cycle is defined at 8 hours, 3 cycles / 24 hours for 10d. with 25 °C / 65 °C 95% R.H, without steps 7a & 7b, unpowered  Parts mounted on test-boards, without condensation on parts	±(0.5%+0.05 Ω) for 1% tol. ±(1.0%+0.05 Ω) for 5% tol. <100 mΩ for Jumper
Thermal Shock	MIL-STD-202 Method 107	-55 / +125 °C  Number of cycles required is 300. Devices unmounted  Maximum transfer time is 20 seconds. Dwell time is 15 minutes	±(0.5%+0.05 Ω) for 1% tol. ±(1%+0.05 Ω) for 5% tol. <100 mΩ for Jumper
Short Time Overload	IEC60115-1 4.13	2.5 times of rated voltage or maximum overload voltage whichever is less for 5 seconds at room temperature	±(1.0%+0.05 Ω) No visible damage
Bending	IEC 60115-1 4.33 IEC 60068-2-21	Chips mounted on a 90 mm glass epoxy resin PCB (FR4)  Bending: 0402: 5 mm 0603/0805: 3 mm 1206: 2 mm  Bending time: 60±5 seconds	±(1.0%+0.05 Ω) <100 mΩ for Jumper No visible damage

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Biased Humidity (steady state)	IEC 60115-1 4.37 MIL-STD-202 Method 103	1,000 hours at 85 °C / 85% R.H. 10% operating power Measurement at 24±2 hours after test conclusion	±(3.0%+0.05 Ω)
<b>Solderability</b>			
- Resistance to Soldering Heat	IEC 60115-1 4.18 MIL-STD-202 Method 215	Condition B, no pre-heat of samples Lead-free solder, 260±5 °C, 10±1 seconds immersion time Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	±(0.5%+0.05 Ω) for 1% tol. ±(1.0%+0.05 Ω) for 5% tol. <50 mΩ for Jumper No visible damage
- Wetting	J-STD-002	Electrical test not required Magnification 10X SMD conditions: (a) Method B, aging 4 hours at 155 °C dry heat, lead-free solder bath at 245 °C (b) Method B, dipping at 215 °C for 3 seconds	Well tinned (≥95% covered) No visible damage
ESD	AEC-Q200-002	Human body model, 1 pos. + 1 neg. discharges: 0402/0603: 1 KV 0805/1206: 2 KV	±(3.0%+0.05 Ω)
Terminal Strength	IEC 60115-1 4.32 IEC 60068-2-21	A force of 5N applied for 10±1 seconds	±(1.0%+0.05 Ω)
FOS	ASTM-B-809-95	Sulfur (saturated vapor) 1,000 hours, 60±2 °C, 91-93% R.H., unpowered	±(1.0%+0.05 Ω)

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	Jan 07, 2011	-	- First issue of this specification

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